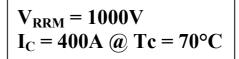
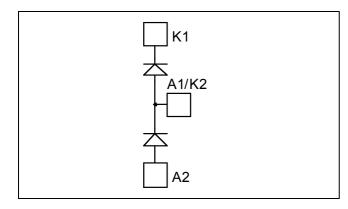


# Diode Phase leg Power Module





A1/K2

#### **Application**

- Anti-Parallel diode
- Uninterruptible Power Supply (UPS)
- Induction heating
- Welding equipment
- High speed rectifiers

#### **Features**

- Ultra fast recovery times
- Soft recovery characteristics
- High blocking voltage
- High current
- Low leakage current
- Very low stray inductance
  - Symmetrical design
  - M5 power connectors
- High level of integration

#### **Benefits**

- Outstanding performance at high frequency operation
- Low losses
- Low noise switching
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- **RoHS Compliant**

## Absolute maximum ratings

Symbol	Parameter			Max ratings	Unit	
$V_R$	Maximum DC reverse Voltage			1000	V	
$V_{RRM}$	Maximum Peak Repetitive Reverse	e Voltage		1000	V	
$I_{F(AV)}$	Maximum Average Forward	Dot1 500/	$T_C = 25^{\circ}C$	500		
	Current	Duty cycle = 50%	$T_C = 70$ °C	400	Α	
I <sub>F(RMS)</sub>	RMS Forward Current	Duty cycle = 50%	$T_C = 45^{\circ}C$	500	Α	
$I_{FSM}$	Non-Repetitive Forward Surge Cu	rrent 8.3ms	$T_C = 45$ °C	3000		

These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com



### All ratings @ $T_j = 25$ °C unless otherwise specified

### **Electrical Characteristics**

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
$V_{\mathrm{F}}$	Diode Forward Voltage	$I_F = 400A$			2.1	2.7	
		$I_F = 600A$			2.3		V
		$I_F = 400A$	$T_{j} = 125^{\circ}C$		1.7		
$I_{RM}$	Maximum Reverse Leakage Current	$V_R = 1000V$ $T_j = 25^{\circ}C$ $T_j = 125^{\circ}C$	$T_i = 25^{\circ}C$			250	^
			$T_j = 125$ °C			1000	μΑ
$C_{T}$	Junction Capacitance	$V_R = 1000V$			480		pF

**Dynamic Characteristics** 

Symbol	Characteristic	Test Conditions		Min	Typ	Max	Unit
$t_{rr}$	Reverse Recovery Time	$I_F=1A, V_R=30V$ $di/dt = 400A/\mu s$	$T_j = 25^{\circ}C$		45		ns
t <sub>rr</sub>	Reverse Recovery Time		$T_j = 25$ °C		290		ns
	Reverse Recovery Time		$T_j = 125$ °C		340		113
Q <sub>rr</sub>	Reverse Recovery Charge $I_F = 400A$ $V_R = 667V$	$T_j = 25$ °C		2.7		μС	
Vп	Reverse Recovery Charge	$di/dt = 800A/\mu s$	$T_j = 125$ °C		14.6		μС
$I_{RRM}$	Reverse Recovery Current	·	$T_j = 25$ °C		24		A
	Reverse Recovery Current		$T_{j} = 125^{\circ}C$		72		
$t_{rr}$	Reverse Recovery Time	$I_F = 400A$ $V_R = 667V$ $di/dt = 4000A/\mu s$			160		ns
Qrr	Reverse Recovery Charge		$T_j = 125$ °C		28.4		μС
$I_{RRM}$	Reverse Recovery Current				280		Α

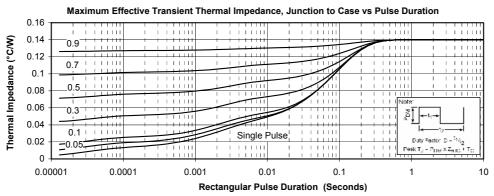
Thermal and package characteristics

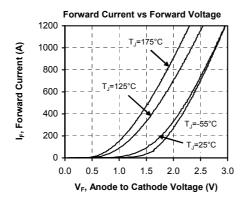
Symbol	Characteristic			Min	Тур	Max	Unit
$R_{thJC}$	Junction to Case Thermal Resistance					0.14	°C/W
$V_{ISOL}$	RMS Isolation Voltage, any terminal to case t =1 min, 50/60Hz			4000			V
$T_{J}$	Operating junction temperature range			-40		175	°C
$T_{STG}$	Storage Temperature Range			-40		125	
$T_{\rm C}$	Operating Case Temperature			-40		100	
Torque	Mounting torque	To heatsink	M6	3		5	N.m
		For terminals	M5	2		3.5	
Wt	Package Weight					300	g

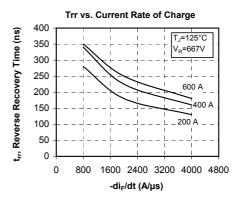
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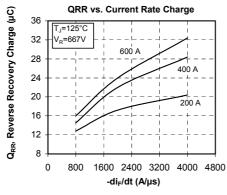


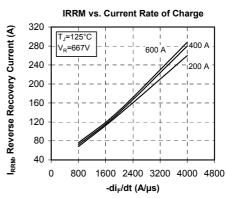
### **Typical Performance Curve**

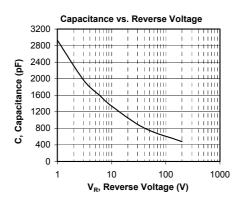


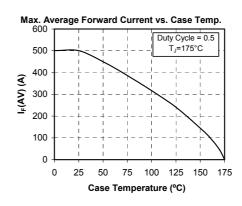






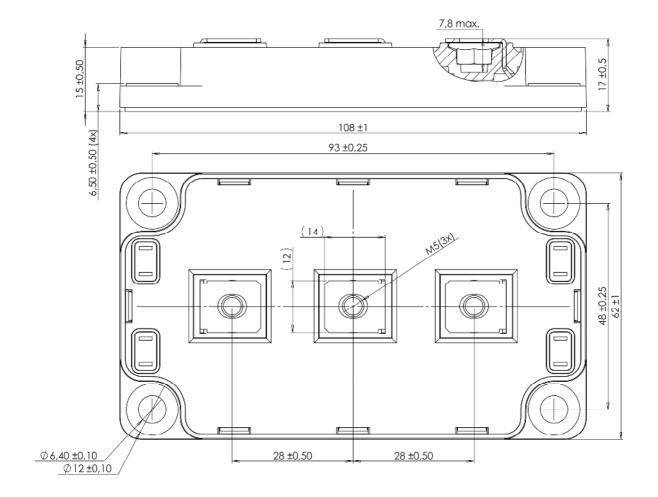








### SP6 Package outline (dimensions in mm)





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